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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of:

Applicant: Dong-Hyuk Ju et al.

Art Unit: 2826

Serial No: 09/879,724

Examiner: Ahmed N. Sefci

Filing Date: June 12, 2001

Confirmation No.: 4898

Title: LEAKY, THERMALLY CONDUCTIVE INSULATOR MATERIAL (LTCIM) IN
SEMICONDUCTOR-ON-INSULATOR (SOI) STRUCTURE

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REPLY TO OFFICE ACTION DATED APRIL 10, 2002

Dear Sir:

Please amend the above-identified application in the following manner.